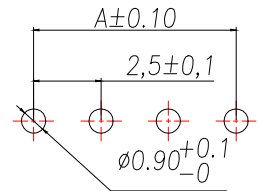
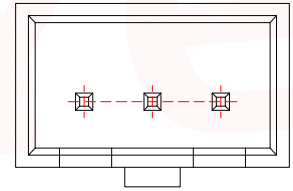
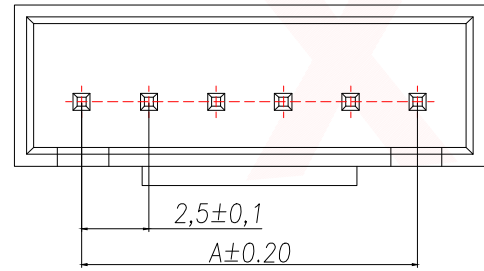
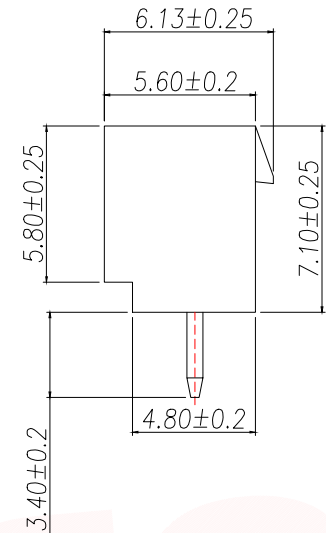
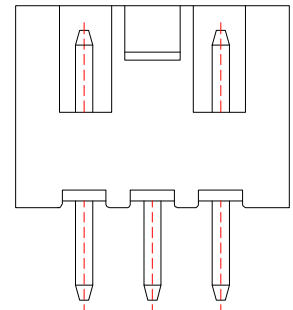
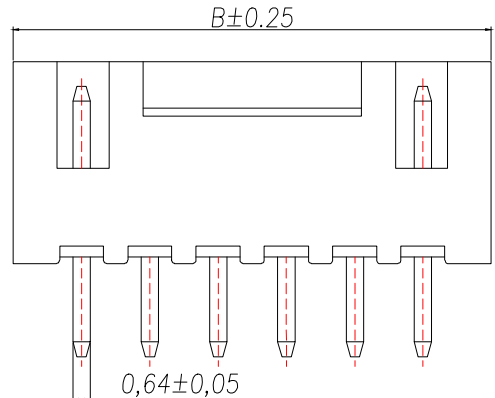


REV.	Q'TY	ECN. NO.	APR.	DATE



SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

- 技术要求:
1. 塑件材料: PA66(UL-94V-0)
  2. 接触件: 黄铜镀锡
  3. 接触电阻:  $\leq 10m\Omega$
  4. 绝缘电阻:  $\geq 100M\Omega$
  5. 额定电压: 250V AC DC
  6. 额定电流: 2.0A AC DC
  7. 耐压: 能承受1000V AC/Minute
  8. 工作温度:  $-25^{\circ}\sim+85^{\circ}$
  9. 可焊性试验: 浸锡面积 $\geq 95\%$  温度235 , 时间 $2.5\pm 0.5$ 秒
  10. 铅和镉等六大有害物质含量要符合环保要求。

Part No	Pin	A	B
XY-XHB2.54-2A11	2	2.50	7.50
XY-XHB2.54-3A11	3	5.00	10.00
XY-XHB2.54-4A11	4	7.50	12.50
XY-XHB2.54-5A11	5	10.00	15.00
XY-XHB2.54-6A11	6	12.50	17.50
XY-XHB2.54-7A11	7	15.00	20.00
XY-XHB2.54-8A11	8	17.50	22.50
XY-XHB2.54-9A11	9	20.00	25.00
XY-XHB2.54-10A11	10	22.50	27.50
XY-XHB2.54-11A11	11	25.00	30.00
XY-XHB2.54-12A11	12	27.50	32.50
XY-XHB2.54-13A11	13	30.00	35.00
XY-XHB2.54-14A11	14	32.50	37.50
XY-XHB2.54-15A11	15	35.00	40.00
XY-XHB2.54-16A11	16	37.50	42.50
XY-XHB2.54-17A11	17	40.00	45.00
XY-XHB2.54-18A11	18	42.50	47.50
XY-XHB2.54-19A11	19	45.00	50.00
XY-XHB2.54-20A11	20	47.50	52.50

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN
1	基座Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyeconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED				
.X±0.35	X.*± 5°	APR.	Alex	TITLE: WAFER XHB2.54MM 带扣 直针
.XX±0.25	.X*± 3°	CHK.	Jack	DWG NO. XY-XHB2.54-NA11
.XXX±0.15	.XX*± 1°	DRA.	Can	PROJ.  CUSTOMER DRAWING
		SIZE A4	SCALE 1:1	SHEET 1/1 REV. A